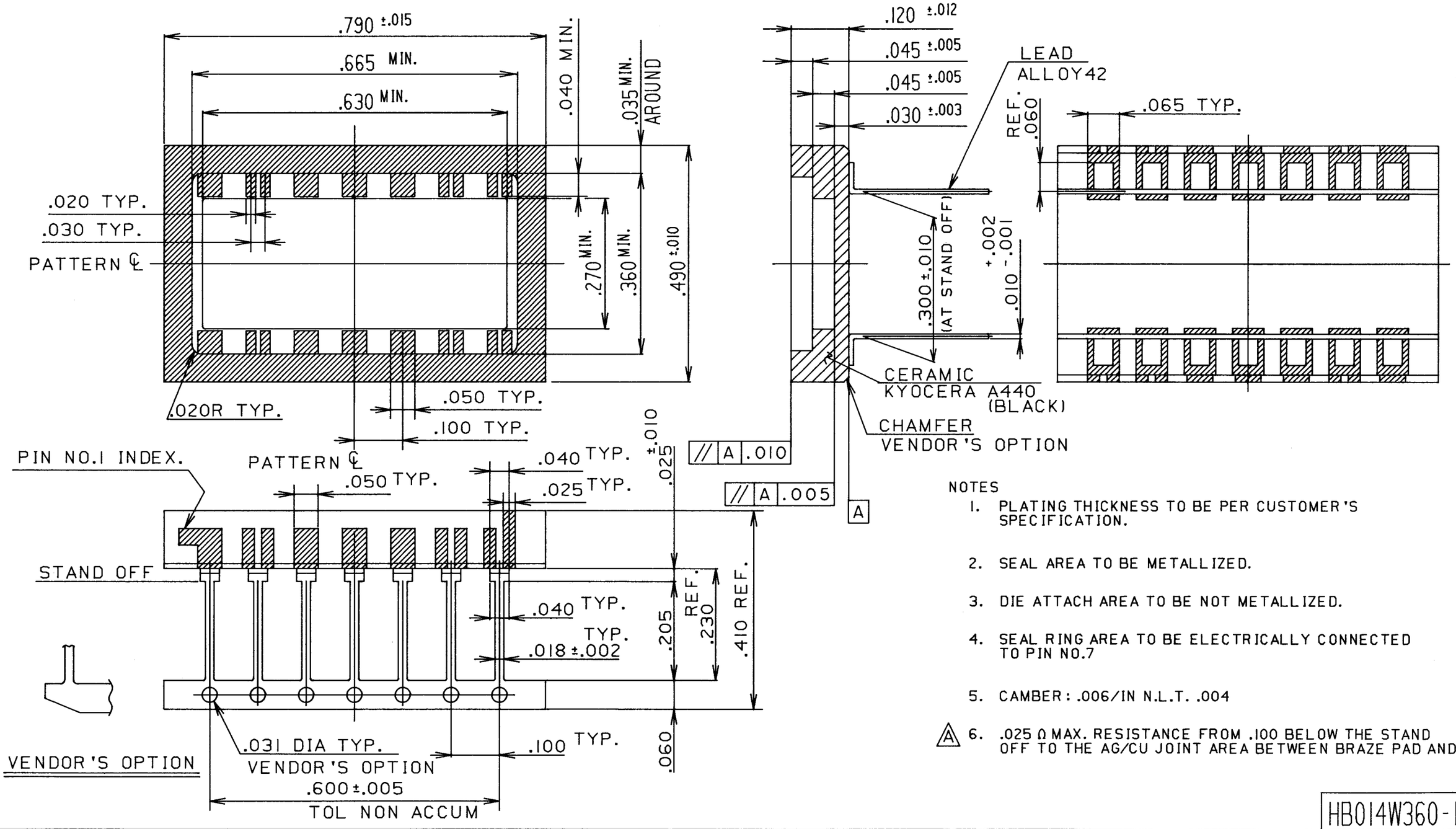

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE NOT METALLIZED.
4. SEAL RING AREA TO BE ELECTRICALLY CONNECTED TO PIN NO.7
5. CAMBER : .006/IN N.L.T. .004
6. (A) .025 Ω MAX. RESISTANCE FROM .100 BELOW THE STAND OFF TO THE AG/CU JOINT AREA BETWEEN BRAZE PAD AND L/F.

HB014W360-1 S=7 D=N

MODIFICATION						
	(A)	ADDED: NOTE 6	JUN.02.'89	S.F	S.T	T.A
		CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME: 14 LEAD HYBRID PACKAGE
SCALE 5/1
MATERIAL: AS INDICATED
TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION

DRAWN	CHECKED	APPROVED	DATE
S.F	K.K	M.K	MAY.16.'89

KYOCERA CORPORATION
KYOTO JAPAN

DRAWING NO. KD-H89360-A
SHEET 1/1